

Application No.: 10/091,945

Docket No.: JCLA6897

In The Specification:

Please amend paragraph [0028] as follows:

[0028] Referring to FIG. 7, a cross-sectional view illustrates a cavity down BGA packaging structure according to a second embodiment of the present invention. In the present embodiment, a ground substrate 520 including an opening 522 is bonded onto the heat spreader ~~500~~510. The opening 522 constitutes a cavity 502 that exposes the heat spreader ~~500~~ 510 at a chip-mounting region 540 into which a chip 560, via its back surface 562, may be bonded onto the heat spreader ~~500~~510. Similar to the previous embodiment, a circuit substrate 550 including at least an insulating layer, a patterned wiring layer, and a plurality of vias is further arranged over a substrate-mounting region 530 located around the chip-mounting region 540. A plurality of ground wires 570 connect the ground pads 564 of the chip 560 to the ground substrate 520.

In The Drawings:

Please substitute the attached clean drawing of Fig. 7 for the pending drawing of Fig. 7. The amended portion is the deletion of the reference number "500".